EPS 2820

HIGH HDT POTTING & ADHESIVE EPOXY SYSTEM

DESCRIPTION

EPS 2820 is a lower viscosity version of EPS 2815 with High HDT properties at lower process temperatures. **EPS 2820** is designed for applications in potting, casting, laminating, filament winding, etc.

FEATURES

Unfilled
Rigid 85 D
Excellent Electrical Properties
HDT 300 Deg F
Good Hydrolytic Stability
Low Viscosity

Liquid Properties	Epoxy 240A	AMN 370B	Mixed
Appearance	Amber Liquid	Amber Liquid	Amber Liquid
Viscosity (cps)	10,000-15,000(77F)	100-200(77F)	8,000-9,000(77F)
Density (lbs/gal)	9.50-9.70	9.00-9.20	9.40-9.60

PHYSICAL PROPERTIES

Hardness, Shore D	85
Dielectric Constant (KHZ)	3.90
Dissipation Factor (KHZ)	0.016
Volume Resistivity ohm-cm	1.22×10^{16}
Dielectric Strength volts/mil	607
ARC Resistance seconds	118
Moisture Resistance	
3 Weeks Immersion H_2O	
Weight Gain	0.7%
Impact Strength, Ft. Lbs/In	0.58
Compressive Strength (psi)	34,200
Tensile Strength (psi)	10,200
Elongation, %	4.40
HDT Deg F	310

EPS 2820 cont:

PROCESSING PARAMETERS

Process Epoxy resin 240A and Amine Hardener 370B between 77 and 200 Deg F.

Mold Temperature: 77 to 200 degrees F.

Mix Ratio: 100 parts Resin 240A to 16.0 parts Amine 370B by weight.

Degas mixture if possible.

Pot Life: (200g mass) (140 Deg F) 30 to 40 minutes.

Demold: 4-5 hours. Demold time maybe shortened by using higher mold and process temperatures.

Post Cure: 2 hours @ 300 Deg F plus 24 hours at 77 Deg F.

STORAGE

Systems should be stored unopened in air tight containers at 60-90 degrees F.

HANDLING PRECAUTIONS

For complete and updated health and safety information, read the MATERIAL SAFETY DATA SHEETS. Do not handle or use until the MATERIAL SAFETY DATA SHEET has been read and understood.